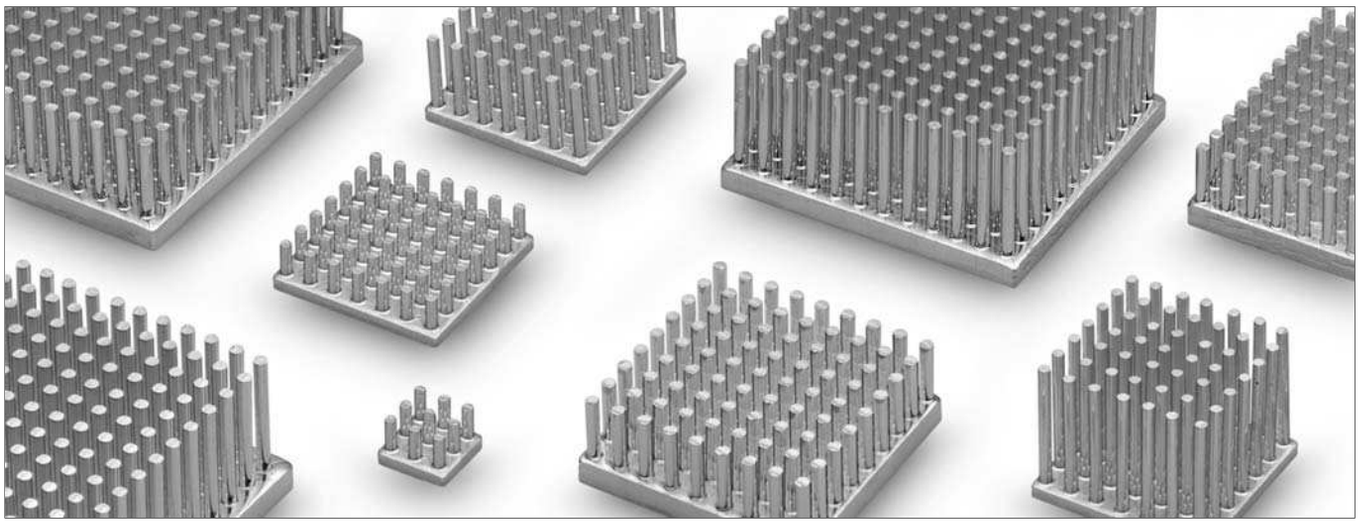
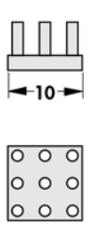
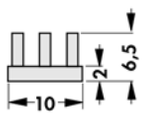
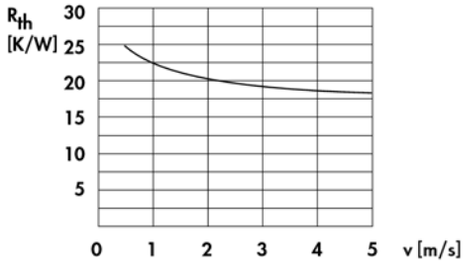
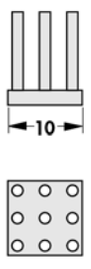
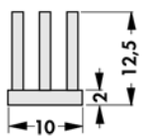
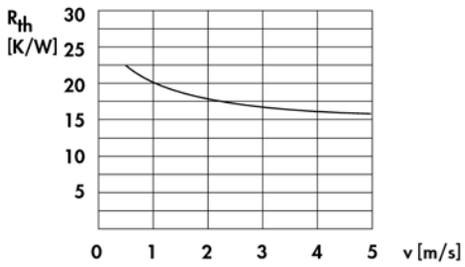
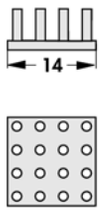
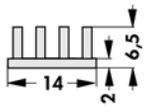
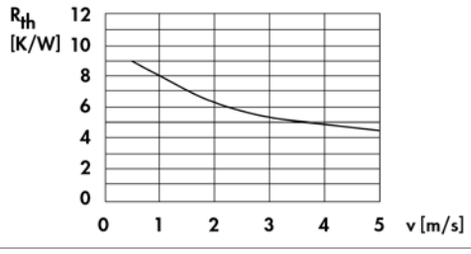
Pin heatsinks



– arrangement and number of pins for optimum air flow
– suitable for forced and free convention
– excellent thermal conductivity by the alloy material (Al99,5; 220 W/mK) and homogeneous arrangement of materials
– constant heat distribution in the base and the pins, in the direction of heat flow
– low weight achieved by optimised geometry
– Components fastened using glue, adhesive foil or clamps

customer-specific modifications and special designs; other pin-lengths and surfaces on request
surface: Al-natural

art. no.			
ICK S 10 x 10 x 6,5 WLF ... 10 x 10 weight: 1 g			
art. no.			
ICK S 10 x 10 x 12,5 WLF ... 10 x 10 weight: 1.3 g			
art. no.			
ICK S 14 x 14 x 6,5 WLF ... 14 x 14 weight: 1.5 g			

Thermal conduct. foil WLFT 404/405 → **E 5**
Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
Processor overview → **B 2 - 7**
SMD-heatsinks → **B 37 – 39**
Mounting material for semiconduct. → **E 35 – 39**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**